

## QIAOXIN N-Channel Super Trench II Power MOSFET

### Description

The series of devices uses **Super Trench II** technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of  $R_{DS(ON)}$  and  $Q_g$ . This device is ideal for high-frequency switching and synchronous rectification.

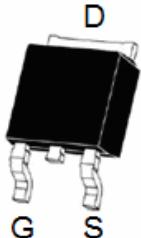
### Application

- DC/DC Converter
- Ideal for high-frequency switching and synchronous rectification

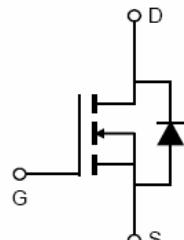
### General Features

- $V_{DS} = 85V, I_D = 75A$
- $R_{DS(ON)} = 8.1m\Omega$ , typical @  $V_{GS} = 10V$
- $R_{DS(ON)} = 10.0m\Omega$ , typical @  $V_{GS} = 4.5V$
- Excellent gate charge  $\times R_{DS(on)}$  product(FOM)
- Very low on-resistance  $R_{DS(on)}$
- 175 °C operating temperature
- Pb-free lead plating

**TO-252**



**Top View**



**Schematic Diagram**

### Package Marking and Ordering Information

Device Marking	Device	Device Package
VCRR080N85AK		TO-252-2L

### Absolute Maximum Ratings ( $T_c=25^\circ C$ unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	$V_{DS}$	85	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	75	A
Drain Current-Continuous( $T_c=100^\circ C$ )	$I_D (100^\circ C)$	55	A
Pulsed Drain Current	$I_{DM}$	300	A
Maximum Power Dissipation	$P_D$	90	W
Derating factor		0.6	W/°C
Single pulse avalanche energy <sup>(Note 4)</sup>	$E_{AS}$	352	mJ
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 To 175	°C

### Thermal Characteristic

Thermal Resistance, Junction-to-Case	$R_{eJC}$	1.67	°C/W
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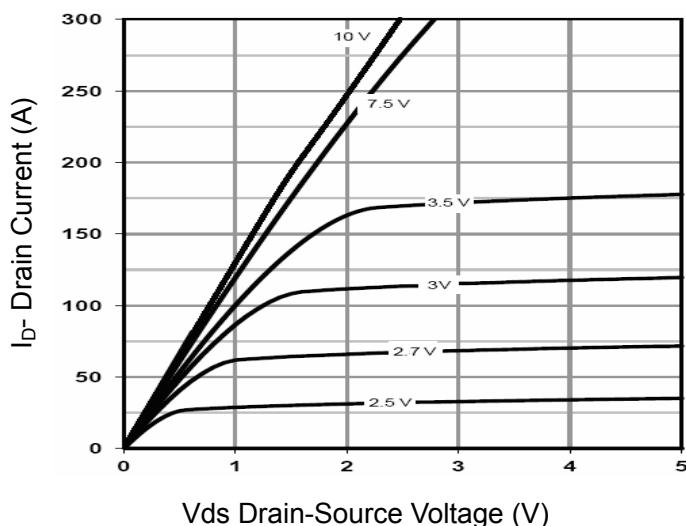
**Electrical Characteristics ( $T_c=25^\circ\text{C}$  unless otherwise noted)**

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$\text{BV}_{\text{DSS}}$	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250\mu\text{A}$	85	-	-	V
Zero Gate Voltage Drain Current	$I_{\text{DSS}}$	$V_{\text{DS}}=85\text{V}, V_{\text{GS}}=0\text{V}$	-	-	1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{\text{GSS}}$	$V_{\text{GS}}=\pm20\text{V}, V_{\text{DS}}=0\text{V}$	-	-	$\pm100$	nA
<b>On Characteristics</b> (Note 3)						
Gate Threshold Voltage	$V_{\text{GS}(\text{th})}$	$V_{\text{DS}}=V_{\text{GS}}, I_{\text{D}}=250\mu\text{A}$	1.2	1.7	2.2	V
Drain-Source On-State Resistance	$R_{\text{DS}(\text{ON})}$	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=37.5\text{A}$	-	8.1	8.5	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=37.5\text{A}$	-	10.0	11.0	$\text{m}\Omega$
Forward Transconductance	$g_{\text{FS}}$	$V_{\text{DS}}=5\text{V}, I_{\text{D}}=37.5\text{A}$		50	-	S
<b>Dynamic Characteristics</b> (Note 3)						
Input Capacitance	$C_{\text{iss}}$	$V_{\text{DS}}=40\text{V}, V_{\text{GS}}=0\text{V}, F=1.0\text{MHz}$	-	2400	-	pF
Output Capacitance	$C_{\text{oss}}$		-	375	-	pF
Reverse Transfer Capacitance	$C_{\text{rss}}$		-	21	-	pF
<b>Switching Characteristics</b> (Note 3)						
Turn-on Delay Time	$t_{\text{d}(\text{on})}$	$V_{\text{DD}}=40\text{V}, I_{\text{D}}=37.5\text{A}$ $V_{\text{GS}}=10\text{V}, R_{\text{G}}=1.6\Omega$	-	14	-	nS
Turn-on Rise Time	$t_r$		-	31	-	nS
Turn-Off Delay Time	$t_{\text{d}(\text{off})}$		-	29	-	nS
Turn-Off Fall Time	$t_f$		-	7	-	nS
Total Gate Charge	$Q_g$	$V_{\text{DS}}=40\text{V}, I_{\text{D}}=37.5\text{A}, V_{\text{GS}}=10\text{V}$	-	39	-	nC
Gate-Source Charge	$Q_{\text{gs}}$		-	13.5	-	nC
Gate-Drain Charge	$Q_{\text{gd}}$		-	11.4	-	nC
<b>Drain-Source Diode Characteristics</b>						
Diode Forward Voltage (Note 2)	$V_{\text{SD}}$	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=37.5\text{A}$	-	-	1.2	V
Diode Forward Current	$I_{\text{S}}$		-	-	75	A
Reverse Recovery Time	$t_{\text{rr}}$	$T_J = 25^\circ\text{C}, I_F = 37.5\text{A}$ $dI/dt = 100\text{A}/\mu\text{s}$ (Note 3)	-	55	-	nS
Reverse Recovery Charge	$Q_{\text{rr}}$		-	98	-	nC

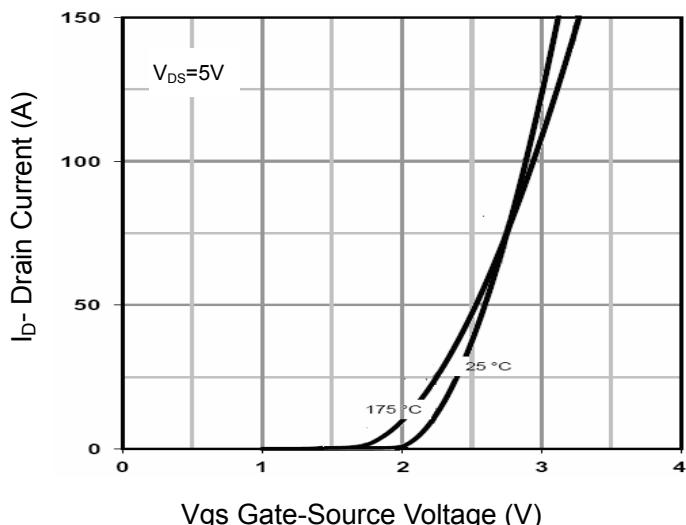
**Notes:**

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
3. Guaranteed by design, not subject to production
4. EAS condition :  $T_J=25^\circ\text{C}, V_{\text{DD}}=50\text{V}, V_G=10\text{V}, L=0.25\text{mH}, R_g=25\Omega$

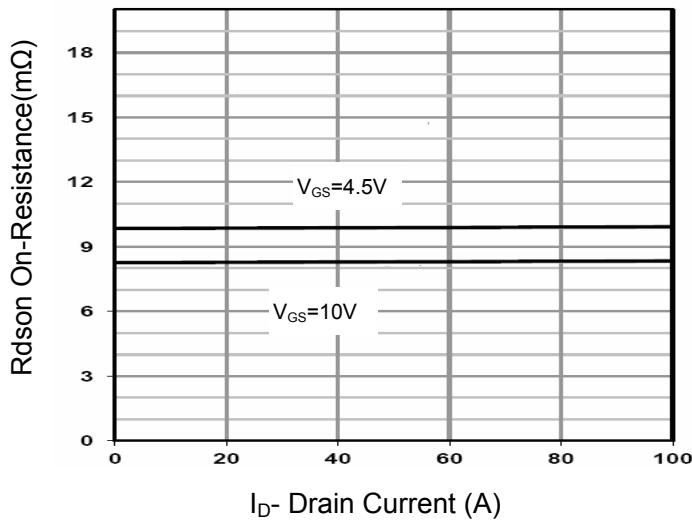
### Typical Electrical and Thermal Characteristics



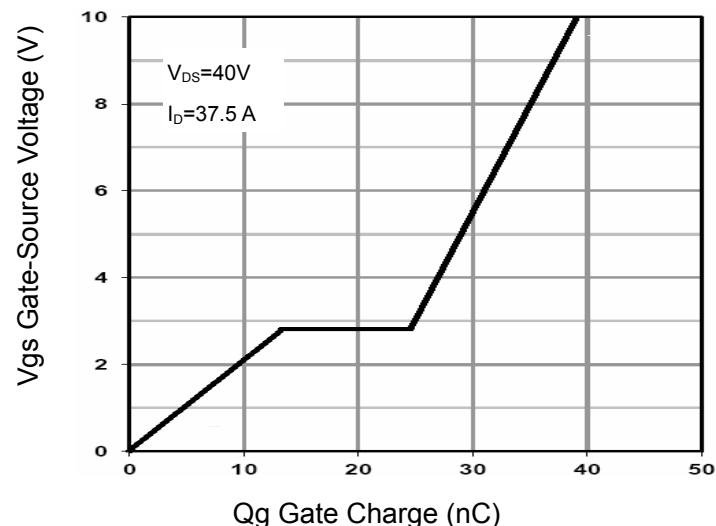
**Figure 1 Output Characteristics**



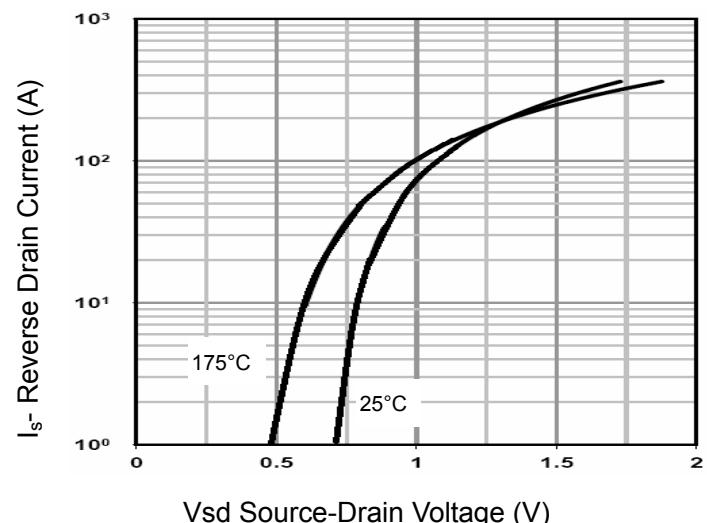
**Figure 2 Transfer Characteristics**



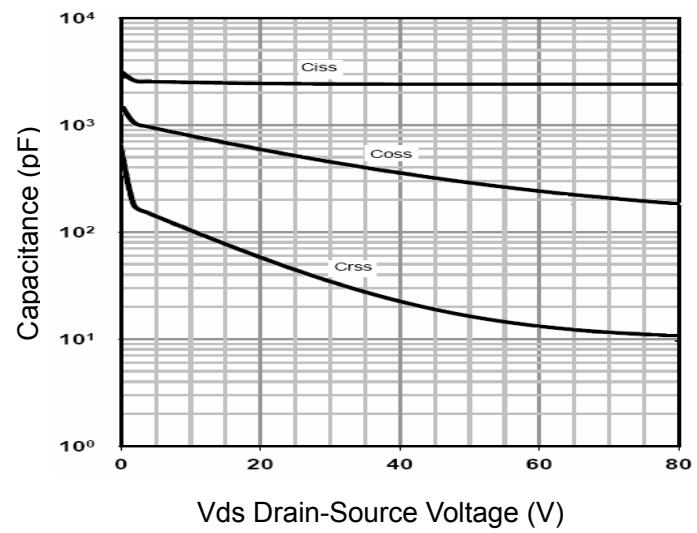
**Figure 3 Rdson- Drain Current**



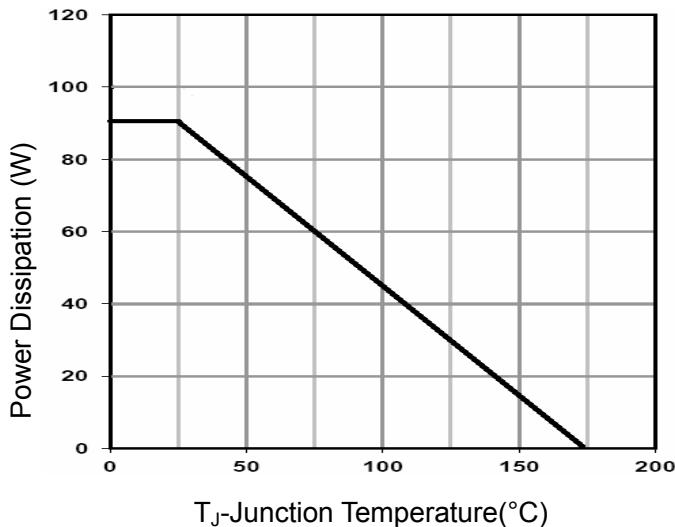
**Figure 4 Gate Charge**



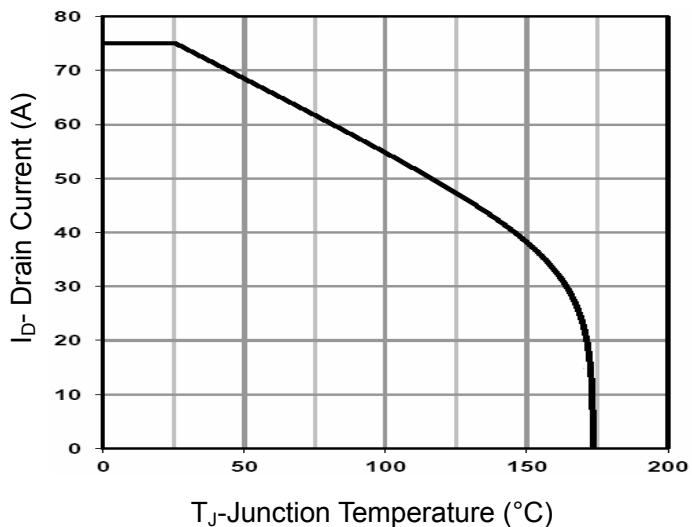
**Figure 5 Source- Drain Diode Forward**



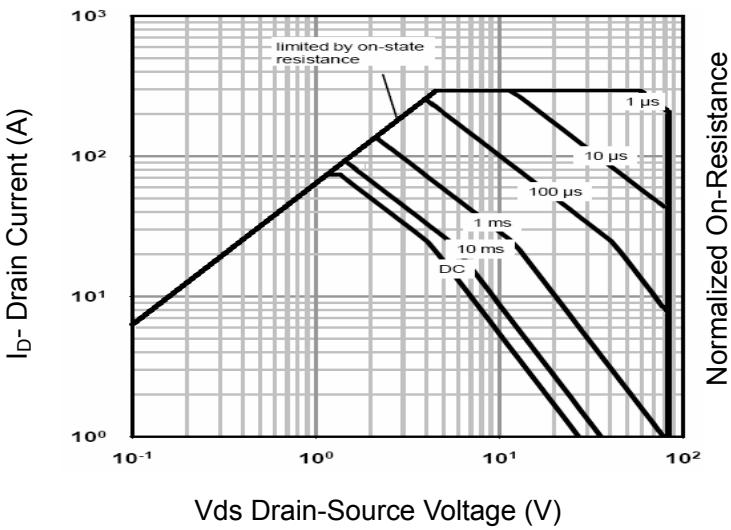
**Figure 6 Capacitance vs VDs**



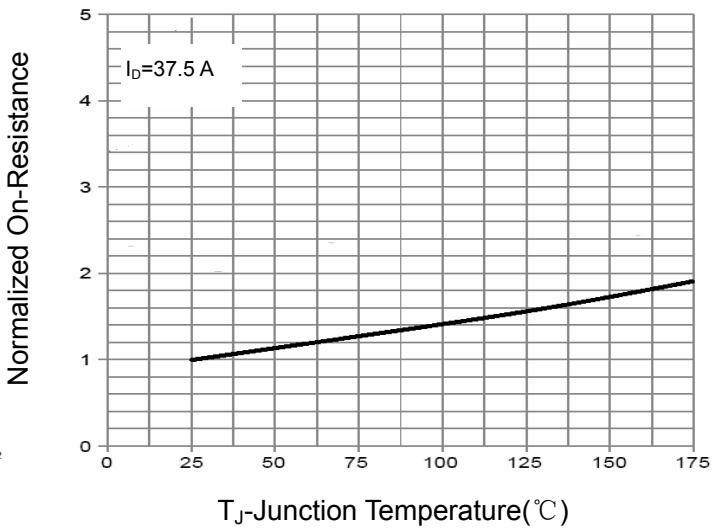
**Figure 7 Power De-rating**



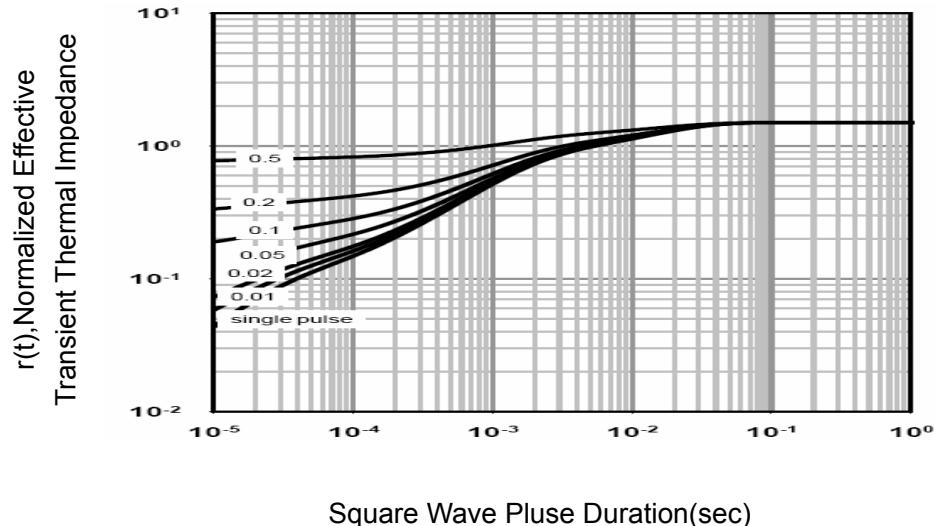
**Figure 9 Current De-rating**



**Figure 8 Safe Operation Area**

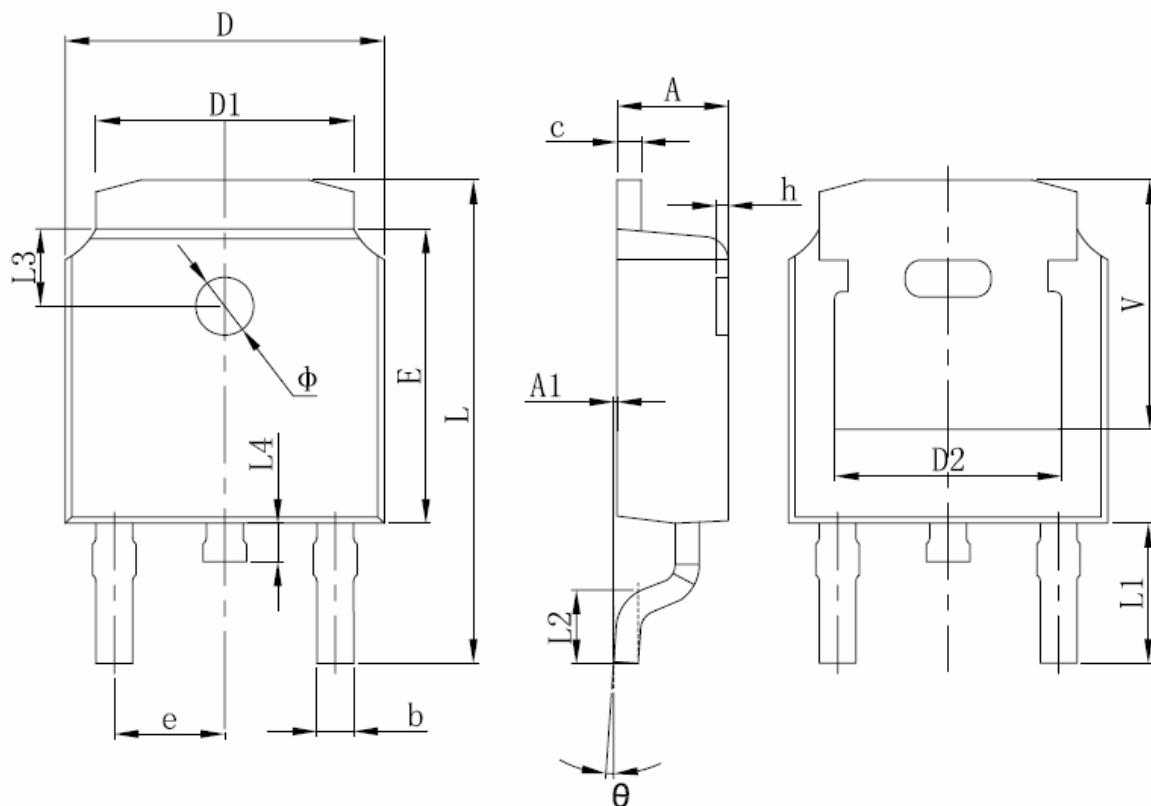


**Figure 10 Rdson-Junction Temperature**



**Figure 11 Transient Thermal Impedance**

## TO-252-2L Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	2.200	2.400	0.087	0.094
A1	0.000	0.127	0.000	0.005
b	0.635	0.770	0.025	0.030
c	0.460	0.580	0.018	0.023
D	6.500	6.700	0.256	0.264
D1	5.100	5.460	0.201	0.215
D2	4.830 REF.		0.190 REF.	
E	6.000	6.200	0.236	0.244
e	2.186	2.386	0.086	0.094
L	9.712	10.312	0.382	0.406
L1	2.900 REF.		0.114 REF.	
L2	1.400	1.700	0.055	0.067
L3	1.600 REF.		0.063 REF.	
L4	0.600	1.000	0.024	0.039
φ	1.100	1.300	0.043	0.051
θ	0°	8°	0°	8°
h	0.000	0.300	0.000	0.012
V	5.250 REF.		0.207 REF.	

### **Attention**

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